Mark J Kushner

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

210	8,880	50	84
papers	citations	h-index	g-index

236	9,994	2.9	6.58
ext. papers	ext. citations	avg, IF	L-index

#	Paper	IF	Citations
210	Particle trapping, size-filtering, and focusing in the nonthermal plasma synthesis of sub-10 nanometer particles. *Journal Physics D: Applied Physics*, **2022**, 55, 235202	3	1
209	Atmospheric pressure plasma functionalization of polystyrene. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2022**, 40, 043001	2.9	0
208	Positive charging of grains in an afterglow plasma is enhanced by ions drifting in an electric field. *Physics of Plasmas*, **2021**, 28, 103702	2.1	4
207	Scaling of silicon nanoparticle growth in low temperature flowing plasmas. *Journal of Applied Physics*, **2021**, 130, 163302	2.5	2
206	Guided plasma jets directed onto wet surfaces: angular dependence and control. *Journal Physics D: Applied Physics*, **2021**, 54, 045206	3	2
205	Interactions between atmospheric pressure plasmas and metallic catalyst particles in packed bed reactors. *Journal Physics D: Applied Physics*, **2021**, 54, 104001	3	7
204	Propagation of atmospheric pressure plasmas through interconnected pores in dielectric materials. *Journal of Applied Physics*, **2021**, 129, 143302	2.5	1
203	Plasma-driven solution electrolysis. *Journal of Applied Physics*, **2021**, 129, 200902	2.5	13
202	Scaling of atomic layer etching of SiO2 in fluorocarbon plasmas: Transient etching and surface roughness. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2021**, 39, 033003	2.9	1
201	Propagation of positive discharges in an air bubble having an embedded water droplet. *Plasma Sources Science and Technology*, **2021**, 30, 015005	3.5	4
200	Electric field reversals resulting from voltage waveform tailoring in Ar/O2 capacitively coupled plasmas sustained in asymmetric systems. *Plasma Sources Science and Technology*, **2021**, 30, 085002	3.5	2
199	Plasma-enhanced atomic layer deposition of SiO2 film using capacitively coupled Ar/O2 plasmas: A computational investigation. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2021**, 39, 052403	2.9	0
198	Erosion of focus rings in capacitively coupled plasma etching reactors. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2021**, 39, 063002	2.9	0
197	Transients using low-high pulsed power in inductively coupled plasmas. *Plasma Sources Science and Technology*, **2020**, 29, 085006	3.5	3
196	Highly selective Si3N4/SiO2 etching using an NF3/N2/O2/H2 remote plasma. I. Plasma source and critical fluxes. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2020**, 38, 023007	2.9	14
195	Pattern dependent profile distortion during plasma etching of high aspect ratio features in SiO2. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2020**, 38, 023001	2.9	10
194	Highly selective Si3N4/SiO2 etching using an NF3/N2/O2/H2 remote plasma. II. Surface reaction mechanism. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2020**, 38, 023008	2.9	7

193	Scaling of pulsed nanosecond capillary plasmas at different specific energy deposition. *Plasma Sources Science and Technology*, **2020**, 29, 125006	3.5	4
192	Helium plasma jet interactions with water in well plates. *Plasma Processes and Polymers*, **2020**, 17, 1900179	3.4	11
191	Generation of reactive species in water film dielectric barrier discharges sustained in argon, helium, air, oxygen and nitrogen. *Journal Physics D: Applied Physics*, **2020**, 53, 435206	3	8
190	Ionization wave propagation in a He plasma jet in a controlled gas environment. *Journal of Applied Physics*, **2020**, 128, 083301	2.5	8
189	Formation of surface ionization waves in a plasma enhanced packed bed reactor for catalysis applications. *Chemical Engineering Journal*, **2020**, 382, 123038	14.7	9
188	Power matching to pulsed inductively coupled plasmas. *Journal of Applied Physics*, **2020**, 127, 133302	2.5	8
187	Ionization wave propagation in an atmospheric pressure plasma multi-jet. *Plasma Sources Science and Technology*, **2019**, 28, 125009	3.5	19
186	Three-dimensional measurements of plasma parameters in an inductively coupled plasma processing chamber. *Physics of Plasmas*, **2019**, 26, 103503	2.1	14
185	Filamentation of capacitively coupled plasmas in large magnetic fields. *Physics of Plasmas*, **2019**, 26, 063515	2.1	10
184	Atmospheric pressure plasma activation of water droplets. *Journal Physics D: Applied Physics*, **2019**, 52, 355207	3	36
183	Plasma etching of high aspect ratio features in SiO_2 using $Ar/C_4F_8/O_2$ mixtures: A computational investigation. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2019**, 37, 031304	2.9	30
182	Microneedle Penetrating Array with Axon-Sized Dimensions for Cuff-less Peripheral Nerve Interfacing **2019**,		4
181	Plasma kinetics in a nanosecond pulsed filamentary discharge sustained in Ar[illegible]H_2O and H_2O. *Journal Physics D: Applied Physics*, **2019**, 52, 044003	3	22
180	Atmospheric pressure plasma jets onto a reactive water layer over tissue: pulse repetition rate as a control mechanism. *Journal Physics D: Applied Physics*, **2019**, 52, 015201	3	18
179	Downstream etching of silicon nitride using continuous-wave and pulsed remote plasma sources sustained in $Ar/NF_3/O_2$ mixtures. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2018**, 36, 021305	2.9	13
178	Interaction of positive streamers in air with bubbles floating on liquid surfaces: conductive and dielectric bubbles. *Plasma Sources Science and Technology*, **2018**, 27, 015016	3.5	6
177	Consequences of atomic layer etching on wafer scale uniformity in inductively coupled plasmas. *Journal Physics D: Applied Physics*, **2018**, 51, 155201	3	10
176	Time-resolved evolution of micro-discharges, surface ionization waves and plasma propagation in a two-dimensional packed bed reactor. *Plasma Sources Science and Technology*, **2018**, 27, 085002	3.5	14

175	A general memristor-based partial differential equation solver. *Nature Electronics*, **2018**, 1, 411-420	28.4	112
174	Spatio-temporal plasma heating mechanisms in a radio frequency electrothermal microthruster. *Plasma Sources Science and Technology*, **2018**, 27, 085011	3.5	6
173	Numerical study of the influence of surface reaction probabilities on reactive species in an rf atmospheric pressure plasma containing humidity. *Plasma Physics and Controlled Fusion*, **2018**, 60, 014035	2	13
172	Molecular admixtures and impurities in atmospheric pressure plasma jets. *Journal of Applied Physics* , **2018**, 124, 153303	2.5	34
171	Transient behavior in quasi-atomic layer etching of silicon dioxide and silicon nitride in fluorocarbon plasmas. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2018**, 36, 06B101	2.9	28
170	Electrode configurations in atmospheric pressure plasma jets: production of reactive species. *Plasma Sources Science and Technology*, **2018**, 27, 105020	3.5	27
169	Chemical kinetics in an atmospheric pressure helium plasma containing humidity. *Physical Chemistry Chemical Physics*, **2018**, 20, 24263-24286	3.6	38
168	Controlling VUV photon fluxes in pulsed inductively coupled Ar/Cl2plasmas and potential applications in plasma etching. *Plasma Sources Science and Technology*, **2017**, 26, 024005	3.5	27
167	Role of neutral transport in aspect ratio dependent plasma etching of three-dimensional features. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2017**, 35, 05C301	2.9	30
166	Propagation of negative electrical discharges through 2-dimensional packed bed reactors. *Journal Physics D: Applied Physics*, **2017**, 50, 025203	3	43
165	Atomic layer etching of 3D structures in silicon: Self-limiting and nonideal reactions. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2017**, 35, 031306	2.9	33
164	Calculated cross sections for electron collisions with NF3, NF2and NF with applications to remote plasma sources. *Plasma Sources Science and Technology*, **2017**, 26, 065010	3.5	27
163	Insights to scaling remote plasma sources sustained in NF3 mixtures. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2017**, 35, 031302	2.9	16
162	The role of thermal energy accommodation and atomic recombination probabilities in low pressure oxygen plasmas. *Plasma Physics and Controlled Fusion*, **2017**, 59, 024004	2	12
161	Investigation of feature orientation and consequences of ion tilting during plasma etching with a three-dimensional feature profile simulator. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2017**, 35, 021303	2.9	25
160	Enhanced control of the ionization rate in radio-frequency plasmas with structured electrodes via tailored voltage waveforms. *Plasma Sources Science and Technology*, **2017**, 26, 125005	3.5	9
159	Properties of arrays of microplasmas: application to control of electromagnetic waves. *Plasma Sources Science and Technology*, **2017**, 26, 105006	3.5	8
158	Effects of a chirped bias voltage on ion energy distributions in inductively coupled plasma reactors. *Journal of Applied Physics*, **2017**, 122, 083301	2.5	4

157	Plasma-induced flow instabilities in atmospheric pressure plasma jets. *Applied Physics Letters*, **2017**, 111, 114101	3.4	38
156	Electron collisions with atoms, ions, molecules, and surfaces: Fundamental science empowering advances in technology. *Proceedings of the National Academy of Sciences of the United States of America*, **2016**, 113, 7026-34	11.5	70
155	Synthesis of Silicon Nanoparticles in Nonthermal Capacitively-Coupled Flowing Plasmas: Processes and Transport. *Plasma Chemistry and Plasma Processing*, **2016**, 36, 941-972	3.6	19
154	Helium atmospheric pressure plasma jets interacting with wet cells: delivery of electric fields. *Journal Physics D: Applied Physics*, **2016**, 49, 185201	3	49
153	The consequences of air flow on the distribution of aqueous species during dielectric barrier discharge treatment of thin water layers. *Plasma Sources Science and Technology*, **2016**, 25, 055020	3.5	16
152	Air plasma treatment of liquid covered tissue: long timescale chemistry. *Journal Physics D: Applied Physics*, **2016**, 49, 425204	3	99
151	Long-term effects of multiply pulsed dielectric barrier discharges in air on thin water layers over tissue: stationary and random streamers. *Journal Physics D: Applied Physics*, **2015**, 48, 494002	3	36
150	Helium atmospheric pressure plasma jets touching dielectric and metal surfaces. *Journal of Applied Physics*, **2015**, 118, 013301	2.5	125
149	Propagation mechanisms of guided streamers in plasma jets: the influence of electronegativity of the surrounding gas. *Plasma Sources Science and Technology*, **2015**, 24, 035022	3.5	67
148	Controlling VUV photon fluxes in low-pressure inductively coupled plasmas. *Plasma Sources Science and Technology*, **2015**, 24, 034017	3.5	31
147	Formation of reactive oxygen and nitrogen species by repetitive negatively pulsed helium atmospheric pressure plasma jets propagating into humid air. *Plasma Sources Science and Technology*, **2015**, 24, 035026	3.5	100
146	Atmospheric pressure plasma jets interacting with liquid covered tissue: touching and not-touching the liquid. *Journal Physics D: Applied Physics*, **2014**, 47, 475203	3	140
145	Branching and path-deviation of positive streamers resulting from statistical photon transport. *Plasma Sources Science and Technology*, **2014**, 23, 065041	3.5	25
144	Investigation of capillary nanosecond discharges in air at moderate pressure: comparison of experiments and 2D numerical modelling. *Journal Physics D: Applied Physics*, **2014**, 47, 365202	3	24
143	Atmospheric pressure dielectric barrier discharges interacting with liquid covered tissue. *Journal Physics D: Applied Physics*, **2014**, 47, 165201	3	150
142	Experimental and numerical study of fast gas heating and O atom production in a capillary nanosecond discharge **2014**,		4
141	Electron energy distributions in a magnetized inductively coupled plasma. *Physics of Plasmas*, **2014**, 21, 093512	2.1	13
140	Electron current extraction from radio frequency excited micro-dielectric barrier discharges. *Journal of Applied Physics*, **2013**, 113, 033301	2.5	8

139	2-dimensional ion velocity distributions measured by laser-induced fluorescence above a radio-frequency biased silicon wafer. *Physics of Plasmas*, **2013**, 20, 083506	2.1	6
138	Space and phase resolved ion energy and angular distributions in single- and dual-frequency capacitively coupled plasmas. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2013**, 31, 061311	2.9	15
137	Ion activation energy delivered to wounds by atmospheric pressure dielectric-barrier discharges: sputtering of lipid-like surfaces. *Journal Physics D: Applied Physics*, **2012**, 45, 115203	3	55
136	Control of electron energy distributions and plasma characteristics of dual frequency, pulsed capacitively coupled plasmas sustained in Ar and Ar/CF_4/O_2. *Plasma Sources Science and Technology* , **2012**, 21, 055028	3.5	30
135	The 2012 Plasma Roadmap. *Journal Physics D: Applied Physics*, **2012**, 45, 253001	3	425
134	Observations of electric discharge streamer propagation and capillary oscillations on the surface of air bubbles in water. *Journal Physics D: Applied Physics*, **2011**, 44, 082001	3	64
133	Experimental and modeling analysis of fast ionization wave discharge propagation in a rectangular geometry. *Physics of Plasmas*, **2011**, 18, 083505	2.1	62
132	Ionization wave propagation on a micro cavity plasma array. *Applied Physics Letters*, **2011**, 99, 141504	3.4	16
131	Modeling of implantation and mixing damage during etching of SiO_2 over Si in fluorocarbon plasmas. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2011**, 29, 051306	2.9	19
130	Dynamics of Dielectric Barrier Discharges Over Wounded Skin. *IEEE Transactions on Plasma Science*, **2011**, 39, 2964-2965	1.3	5
129	Time-Resolved Electron Energy Distributions and Plasma Characteristics in a Pulsed Capacitively Coupled Plasma. *IEEE Transactions on Plasma Science*, **2011**, 39, 2542-2543	1.3	1
128	Fundamentals of gas phase plasmas for treatment of human tissue. *Studies in Health Technology and Informatics*, **2011**, 163, 297-303	0.5	2
127	450 mm dual frequency capacitively coupled plasma sources: Conventional, graded, and segmented electrodes. *Journal of Applied Physics*, **2010**, 108, 113306	2.5	43
126	High energy electron fluxes in dc-augmented capacitively coupled plasmas. II. Effects on twisting in high aspect ratio etching of dielectrics. *Journal of Applied Physics*, **2010**, 107, 023309	2.5	45
125	High energy electron fluxes in dc-augmented capacitively coupled plasmas I. Fundamental characteristics. *Journal of Applied Physics*, **2010**, 107, 023308	2.5	21
124	Fluorine Plasma Treatments of Polypropylene Films, 1 Surface Characterization. *Plasma Processes and Polymers*, **2010**, 7, 107-122	3.4	25
123	Fluorine Plasma Treatments of Poly(propylene) Films, 2 Modeling Reaction Mechanisms and Scaling. *Plasma Processes and Polymers*, **2010**, 7, 123-150	3.4	23
122	Plasma atomic layer etching using conventional plasma equipment. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2009**, 27, 37-50	2.9	123

121	Hybrid modelling of low temperature plasmas for fundamental investigations and equipment design. *Journal Physics D: Applied Physics*, **2009**, 42, 194013	3	222
120	Structure of positive streamers inside gaseous bubbles immersed in liquids. *Journal Physics D: Applied Physics*, **2009**, 42, 132003	3	82
119	Microdischarges for use as microthrusters: modelling and scaling. *Journal Physics D: Applied Physics*, **2008**, 41, 105208	3	19
118	Ion energy and angular distributions into the wafer□focus ring gap in capacitively coupled discharges. *Journal Physics D: Applied Physics*, **2008**, 41, 062004	3	18
117	Seasoning of plasma etching reactors: Ion energy distributions to walls and real-time and run-to-run control strategies. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2008**, 26, 498-512	2.9	36
116	Continuous processing of polymers in repetitively pulsed atmospheric pressure discharges with moving surfaces and gas flow. *Journal Physics D: Applied Physics*, **2007**, 40, 6953-6968	3	36
115	Penetration of plasma into the wafer-focus ring gap in capacitively coupled plasmas. *Journal of Applied Physics*, **2007**, 101, 113307	2.5	21
114	Characteristics of pulsed plasma doping sources for ultrashallow junction formation. *Journal of Applied Physics*, **2007**, 101, 063305	2.5	7
113	Multi-scale simulation of functionalization of rough polymer surfaces using atmospheric pressure plasmas. *Journal Physics D: Applied Physics*, **2006**, 39, 1594-1598	3	23
112	Streamer dynamics in gases containing dust particles. *Plasma Sources Science and Technology*, **2006**, 15, 591-602	3.5	50
111	Integrated feature scale modeling of plasma processing of porous and solid SiO_2. II. Residual fluorocarbon polymer stripping and barrier layer deposition. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2004**, 22, 1260-1274	2.9	16
110	Properties of c-C_4F_8 inductively coupled plasmas. II. Plasma chemistry and reaction mechanism for modeling of Ar/c-C_4F_8/O_2 discharges. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2004**, 22, 511	2.9	96
109	Pulsed plasmas as a method to improve uniformity during materials processing. *Journal of Applied Physics*, **2004**, 96, 82-93	2.5	41
108	Modeling of magnetically enhanced capacitively coupled plasma sources: Ar/C_4F_8/O_2 discharges. *Journal of Applied Physics*, **2004**, 95, 834-845	2.5	29
107	A Monte Carlo simulation of radiation trapping in electrodeless gas discharge lamps. *Journal Physics D: Applied Physics*, **2004**, 37, 1780-1791	3	22
106	Integrated feature scale modeling of plasma processing of porous and solid SiO_2. I. Fluorocarbon etching. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2004**, 22, 1242-1259	2.9	46
105	Modeling of microdischarge devices: Pyramidal structures. *Journal of Applied Physics*, **2004**, 95, 846-859	2.5	123
104	O_2(□) production in He□2 mixtures in flowing low pressure plasmas. *Journal of Applied Physics*, **2004**, 96, 2451-2465	2.5	210

103	A Comparison of Corona-Treated and Flame-Treated Polypropylene Films. *Plasmas and Polymers*, **2003**, 8, 61-95		134
102	A model for plasma modification of polypropylene using atmospheric pressure discharges. *Journal Physics D: Applied Physics*, **2003**, 36, 666-685	3	349
101	Influence of modeling and simulation on the maturation of plasma technology: Feature evolution and reactor design. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2003**, 21, S152-S156	2.9	31
100	Modeling of magnetically enhanced capacitively coupled plasma sources: Ar discharges. *Journal of Applied Physics*, **2003**, 94, 1436-1447	2.5	61
99	Angular anisotropy of electron energy distributions in inductively coupled plasmas. *Journal of Applied Physics*, **2003**, 94, 5522-5529	2.5	15
98	Harmonic content and time variation of electron energy distributions in high-plasma-density, low-pressure inductively coupled discharges. *Journal of Applied Physics*, **2003**, 94, 2223-2233	2.5	5
97	Self-consistent three-dimensional model of dust particle transport and formation of Coulomb crystals in plasma processing reactors. *Journal of Applied Physics*, **2002**, 92, 6451-6460	2.5	33
96	Two-dimensional modeling of long-term transients in inductively coupled plasmas using moderate computational parallelism. II. Ar/Cl2 pulsed plasmas. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2002**, 20, 325-334	2.9	36
95	Two-dimensional modeling of long-term transients in inductively coupled plasmas using moderate computational parallelism. I. Ar pulsed plasmas. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2002**, 20, 313-324	2.9	38
94	Monte Carlo Simulation of the Electrodeposition of Copper. *Journal of the Electrochemical Society*, **2002**, 149, C396	3.9	30
93	Electron energy distributions and anomalous skin depth effects in high-plasma-density inductively coupled discharges. *Physical Review E*, **2002**, 66, 066411	2.4	44
92	Investigations of surface reactions during C2F6 plasma etching of SiO2 with equipment and feature scale models. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2001**, 19, 524-538	2.9	123
91	Trench filling by ionized metal physical vapor deposition. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2001**, 19, 2652-2663	2.9	55
90	Noncollisional heating and electron energy distributions in magnetically enhanced inductively coupled and helicon plasma sources. *Journal of Applied Physics*, **2001**, 90, 3699-3712	2.5	36
89	Pulsed inductively coupled chlorine plasmas in the presence of a substrate bias. *Applied Physics Letters*, **2001**, 79, 2145-2147	3.4	21
88	Wave propagation and power deposition in magnetically enhanced inductively coupled and helicon plasma sources. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2001**, 19, 76-86	2.9	48
87	Inflight electron impact excitation in ionized metal physical vapor deposition. *Journal of Applied Physics*, **2001**, 89, 878-882	2.5	10
86	Mechanisms for CF2 radical generation and loss on surfaces in fluorocarbon plasmas. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2000**, 18, 2661-2668	2.9	55

85	A Monte-Carlo model of xenon resonance radiation transport in a plasma display panel cell: Transition from optically thick to thin regimes. *Journal of Applied Physics*, **2000**, 87, 2700-2707	2.5	14
84	Plasma abatement of perfluorocompounds in inductively coupled plasma reactors. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **2000**, 18, 213-231	2.9	59
83	Interaction between soot particles and NOx during dielectric barrier discharge plasma remediation of simulated diesel exhaust. *Journal of Applied Physics*, **2000**, 88, 6060-6071	2.5	49
82	Consequences of propene and propane on plasma remediation of NOx. *Journal of Applied Physics*, **2000**, 88, 3739-3747	2.5	57
81	Controller design issues in the feedback control of radio frequency plasma processing reactors. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **1999**, 17, 704-712	2.9	12
80	Dynamics of a coplanar-electrode plasma display panel. II. Cell optimization. *Journal of Applied Physics*, **1999**, 85, 3470-3476	2.5	60
79	Design issues in ionized metal physical vapor deposition of copper. *Journal of Applied Physics*, **1998**, 83, 35-43	2.5	54
78	The effect of radio frequency plasma processing reactor circuitry on plasma characteristics. *Journal of Applied Physics*, **1998**, 83, 5087-5094	2.5	54
77	Diagnostic technique for measuring plasma parameters near surfaces in radio frequency discharges. *Applied Physics Letters*, **1998**, 73, 2730-2732	3.4	9
76	Comparison of two-dimensional and three-dimensional models for profile simulation of poly-Si etching of finite length trenches. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **1998**, 16, 3274-3280	2.9	17
75	Consequences of three-dimensional physical and electromagnetic structures on dust particle trapping in high plasma density material processing discharges. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **1998**, 16, 2454-2462	2.9	14
74	Ion composition of expanding microdischarges in dielectric barrier discharges. *Journal of Applied Physics*, **1998**, 83, 7522-7532	2.5	35
73	Multiple microdischarge dynamics in dielectric barrier discharges. *Journal of Applied Physics*, **1998**, 84, 4153-4160	2.5	46
72	Plasma transport around dust agglomerates having complex shapes. *Journal of Applied Physics*, **1998**, 83, 5670-5677	2.5	9
71	Reactions in the afterglow of time modulated inductive discharges of Xe and I2 mixtures. *Journal of Applied Physics*, **1998**, 84, 4727-4730	2.5	4
70	Shapes of agglomerates in plasma etching reactors. *Journal of Applied Physics*, **1997**, 81, 5960-5965	2.5	20
69	Integrated plasma equipment model for polysilicon etch profiles in an inductively coupled plasma reactor with subwafer and superwafer topography. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **1997**, 15, 1913-1921	2.9	73
68	A semianalytic radio frequency sheath model integrated into a two-dimensional hybrid model for plasma processing reactors. *Journal of Applied Physics*, **1997**, 81, 569-577	2.5	62

67	Ion-ion neutralization of iodine in radio-frequency inductive discharges of Xe and I2 mixtures. *Journal of Applied Physics*, **1997**, 82, 2150-2155	2.5	3
66	Simulation of the formation of two-dimensional Coulomb liquids and solids in dusty plasmas. *Journal of Applied Physics*, **1997**, 82, 2106-2114	2.5	17
65	Consequences of asymmetric pumping in low pressure plasma processing reactors: A three-dimensional modeling study. *Journal of Applied Physics*, **1997**, 82, 5312-5320	2.5	34
64	Model for noncollisional heating in inductively coupled plasma processing sources. *Journal of Applied Physics*, **1997**, 81, 5966-5974	2.5	51
63	Argon metastable densities in radio frequency Ar, Ar/O2 and Ar/CF4 electrical discharges. *Journal of Applied Physics*, **1997**, 82, 2805-2813	2.5	168
62	Ion drag effects in inductively coupled plasmas for etching. *Applied Physics Letters*, **1996**, 68, 903-905	3.4	32
61	A three-dimensional model for inductively coupled plasma etching reactors: Azimuthal symmetry, coil properties, and comparison to experiments. *Journal of Applied Physics*, **1996**, 80, 1337-1344	2.5	90
60	The effect of CO2 on the plasma remediation of NxOy. *Applied Physics Letters*, **1996**, 68, 2064-2066	3.4	14
59	Formation of XeI(B) in low pressure inductive radio frequency electric discharges sustained in mixtures of Xe and I2. *Journal of Applied Physics*, **1996**, 80, 5593-5597	2.5	18
58	A time dependent propagator method for long mean free path transport of neutral particles in plasma processing reactors. *Journal of Applied Physics*, **1996**, 79, 3423-3431	2.5	6
57	Evidence for inelastic processes for N+3 and N+4 from ion energy distributions in He/N2 radio frequency glow discharges. *Journal of Applied Physics*, **1996**, 79, 93-98	2.5	7
56	Modeling of high power semiconductor switches operated in the nonlinear mode. *Journal of Applied Physics*, **1996**, 79, 2084-2090	2.5	16
55	Predictions of ion energy distributions and radical fluxes in radio frequency biased inductively coupled plasma etching reactors. *Journal of Applied Physics*, **1996**, 79, 2275-2286	2.5	74
54	Regimes of particle trapping in inductively coupled plasma processing reactors. *Applied Physics Letters*, **1996**, 68, 3716-3718	3.4	20
53	Electron-beam controlled radio frequency discharges for plasma processing. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **1996**, 14, 2094-2101	2.9	26
52	A model for transport and agglomeration of particles in reactive ion etching plasma reactors. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **1996**, 14, 562-566	2.9	21
51	Characteristics of an optically activated pulsed power GaAs(Si:Cu) switch obtained by two-dimensional modeling. *Journal of Applied Physics*, **1995**, 77, 3518-3522	2.5	9
50	The effect of subwafer dielectrics on plasma properties in plasma etching reactors. *Journal of Applied Physics*, **1995**, 77, 3668-3673	2.5	17

49	A hybrid model for particle transport and electron energy distributions in positive column electrical discharges using equivalent species transport. *Journal of Applied Physics*, **1995**, 78, 5909-5918	2.5	11
48	Reaction chemistry and optimization of plasma remediation of NxOy from gas streams. *Journal of Applied Physics*, **1995**, 78, 2074-2085	2.5	167
47	Computer simulation of mass-selective plasma-source ion implantation. *Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films*, **1994**, 12, 1380-1386	2.9	0
46	Excitation mechanisms and gain modeling of the high-pressure atomic Ar laser in He/Ar mixtures. *Journal of Applied Physics*, **1994**, 75, 1883-1890	2.5	84
45	Mutual shielding of closely spaced dust particles in low pressure plasmas. *Journal of Applied Physics*, **1994**, 75, 3351-3357	2.5	39
44	Plasma chemistry of He/O2/SiH4 and He/N2O/SiH4 mixtures for remote plasma-activated chemical-vapor deposition of silicon dioxide. *Journal of Applied Physics*, **1993**, 74, 6538-6553	2.5	86
43	Two-dimensional hybrid model of inductively coupled plasma sources for etching. *Applied Physics Letters*, **1993**, 63, 605-607	3.4	123
42	The role of negative ions in the formation of particles in low-pressure plasmas. *Journal of Applied Physics*, **1993**, 74, 853-861	2.5	95
41	Radially dependent solutions of Boltzmann's equation in low-temperature plasmas using a modified two-term expansion. *Journal of Applied Physics*, **1993**, 73, 1080-1090	2.5	38
40	Short pulse electron beam excitation of the high-pressure atomic Ne laser. *Journal of Applied Physics*, **1993**, 73, 8059-8065	2.5	15
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